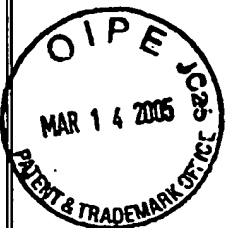


INFORMATION DISCLOSURE CITATION IN AN APPLICATION  (PTO-1449)		ATTY. DOCKET NO. 008019 USA/ MTCG/PCTRL	SERIAL NO. 10/759,108
		APPLICANT Alexander T. SCHWARM	
		FILING DATE January 20, 2004	GROUP 2825 2125
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)			
RJ	November 15, 2004. European Office Action for European Patent Application No. 02752701.9.		
RJ	December 14, 2004. U.S. Notice of Allowance for U.S. Patent Application No. 09/928,474.		
EXAMINER		DATE CONSIDERED	
/Ryan Jarrett/		05/19/2006	

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**INFORMATION DISCLOSURE
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APPLICATION
(PTO-1449)**



ATTY. DOCKET NO.
008019 USA/
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SERIAL NO.
10/759,108

APPLICANT
Alexander T. SCHWARM

FILING DATE
January 20, 2004

GROUP
2825 2125

U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
RJ	4,957,605	09/18/90	Hurwitt et al.			04/17/89
	5,240,552	08/31/93	Yu et al.			12/11/91
	5,369,544	11/29/94	Mastrangelo			04/05/93
	5,444,837	08/22/95	Bomans et al.			12/29/93
	5,665,214	09/09/97	Iturralde			05/03/95
	5,695,810	12/09/97	Dubin et al.			11/20/96
	5,824,599	10/20/98	Schacham-Diamond et al.			01/16/96
	5,825,356	10/20/98	Habib et al.			03/18/96
	5,831,851	11/03/98	Eastburn et al.			03/21/95
	5,838,951	11/17/98	Song			08/28/96
	5,859,777	01/12/99	Yokoyama et al.			05/13/97
	5,871,805	02/16/99	Lemelson			04/08/96
	5,943,550	08/24/99	Fulford, Jr. et al.			03/29/96
	6,012,048	01/04/00	Gustin et al.			05/30/97
	6,037,664	03/14/00	Zhao et al.			03/31/98
	6,059,636	05/09/00	Inaba et al.			07/09/98
	6,096,649	08/01/00	Jang			10/25/99
	6,100,195	08/08/00	Chan et al.			12/28/98
	6,114,238	09/05/00	Liao			05/20/98
	6,150,270	11/21/00	Matsuda et al.			01/07/99
	6,157,864	12/05/00	Schwenke et al.			05/08/98
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	6,226,563 B1	05/01/01	Lim			09/04/98
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	6,259,160 B1	07/10/01	Lopatin et al.			04/21/99
	6,281,127 B1	08/28/01	Shue			04/15/99
EXAMINER				DATE CONSIDERED		

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				APPLICANT Alexander T. SCHWARM			
				FILING DATE January 20, 2004		GROUP 2825	
U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
RJ	6,317,643 B1	11/13/01	Dmochowski			03/31/99	
↓	6,339,727 B1	01/15/02	Ladd			12/21/98	
	6,355,559 B1	03/12/02	Havemann et al.			11/03/00	
	6,391,780 B1	05/21/02	Shih et al.			08/23/99	
	6,417,014 B1	07/09/02	Lam et al.			10/19/99	
	6,427,093 B1	07/30/02	Toprac			10/07/99	
	6,432,728 B1	08/13/02	Tai et al.			10/16/00	
	6,449,524 B1	09/10/02	Miller et al.			01/04/00	
	6,455,415 B1	09/24/02	Lopatin et al.			04/16/01	
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	6,484,064 B1	11/19/02	Campbell			10/05/99	
	6,495,452 B1	12/17/02	Shih			08/18/99	
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	6,515,368 B1	02/04/03	Lopatin et al.			12/07/01	
	6,517,414 B1	02/11/03	Tobin et al.			03/10/00	
	6,528,409 B1	03/04/03	Lopatin et al.			04/29/02	
	6,537,912 B1	03/25/03	Agarwal			08/25/00	
	6,580,958 B1	06/17/03	Takano			11/22/99	
	6,605,549 B2	08/12/03	Leu et al.			09/29/01	
	6,607,976 B2	08/19/03	Chen et al.			09/25/01	
	6,609,946 B1	08/26/03	Tran			07/14/00	
	6,616,513 B1	09/09/03	Osterheld			04/05/01	
	6,624,075 B1	09/23/03	Lopatin et al.			11/05/02	
	6,630,741 B1	10/07/03	Lopatin et al.			12/07/01	
	6,660,633 B1	12/09/03	Lopatin et al.			02/26/02	
	6,708,074 B1	03/16/04	Chi et al.			08/11/00	
	6,708,075 B2	03/16/04	Sonderman et al.			11/16/01	
↓	6,728,587 B2	04/27/04	Goldman et al.			12/27/00	
EXAMINER				DATE CONSIDERED			

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				APPLICANT Alexander T. SCHWARM			
				FILING DATE January 20, 2004		GROUP 2825	
FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
RJ	EP 0 932 195 A1	07/28/99	EP			X	
RJ	EP 1 083 470 A2	03/14/01	EP			X	
RJ	GB 2 365 215 A	02/13/02	GB			X	
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)							
RJ	Sun, S.C. 1998. "CVD and PVD Transition Metal Nitrides as Diffusion Barriers for Cu Metallization." <i>IEEE</i> . pp. 243-246.						
	Tagami, M., A. Furuya, T. Onodera, and Y. Hayashi. 1999. "Layered Ta-nitrides (LTN) Barrier Film by Power Swing Sputtering (PSS) Technique for MOCVD-Cu Damascene Interconnects." <i>IEEE</i> . pp. 635-638.						
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	Eisenbraun, Eric, Oscar van der Straten, Yu Zhu, Katharine Dovidenko, and Alain Kaloyeros. 2001. "Atomic Layer Deposition (ALD) of Tantalum-Based Materials for Zero Thickness Copper Barrier Applications" (Abstract). <i>IEEE</i> . pp. 207-209.						
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	Elers, Kai-Erik, Ville Saanila, Pekka J. Soininen, Wei-Min Li, Juhana T. Kostamo, Suvi Haukka, Jyrki Juhanoja, and Wim F.A. Besling. 2002. "Diffusion Barrier Deposition on a Copper Surface by Atomic Layer Deposition" (Abstract). <i>Advanced Materials</i> . Vol. 14, No. 13-14, pp. 149-153.						
	Peng, C.H., C.H. Hsieh, C.L. Huang, J.C. Lin, M.H. Tsai, M.W. Lin, C.L. Chang, Winston S. Shue, and M.S. Liang. 2002. "A 90nm Generation Copper Dual Damascene Technology with ALD TaN Barrier." <i>IEEE</i> . pp. 603-606.						
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	Wu, Z.C., Y.C. Lu, C.C. Chiang, M.C. Chen, B.T. Chen, G.J. Wang, Y.T. Chen, J.L. Huang, S.M. Jang, and M.S. Liang. 2002. "Advanced Metal Barrier Free Cu Damascene Interconnects with PECVD Silicon Carbide Barriers for 90/65-nm BEOL Technology." <i>IEEE</i> . pp. 595-598.						
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	March 30, 2004. Written Opinion for PCT/US02/19062.						
	April 9, 2004. Written Opinion for PCT/US02/19116.						
	April 22, 2004. Office Action for U.S. Serial No. 09/998,372, filed November 30, 2001.						
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INFORMATION DISCLOSURE
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SERIAL NO.
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APPLICANT
Alexander T. SCHWARM

FILING DATE
January 20, 2004

GROUP
2825 2125

U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
RJ	3,205,485	09/07/65	Noltingk			10/21/60
	3,229,198	01/11/66	Libby			09/28/62
	3,767,900	10/23/73	Chao et al.			06/23/71
	3,920,965	11/18/75	Sohrwardy			03/04/74
	4,000,458	12/28/76	Miller et al.			08/21/75
	4,207,520	06/10/80	Flora et al.			04/06/78
	4,209,744	06/24/80	Gerasimov et al.			03/27/78
	4,302,721	11/24/81	Urbanek et al.			05/15/79
	4,368,510	01/11/83	Anderson			10/20/80
	4,609,870	09/02/86	Lale et al.			09/13/84
	4,616,308	10/07/86	Morshedi et al.			12/02/85
	4,663,703	05/05/87	Axelby et al.			10/02/85
	4,698,766	10/06/87	Entwistle et al.			05/17/85
	4,750,141	06/07/88	Judell et al.			11/26/85
	4,755,753	07/05/88	Chern			07/23/86
	4,757,259	07/12/88	Charpentier			11/05/86
	4,796,194	01/03/89	Atherton			08/20/86
	4,901,218	02/13/90	Cornwell			03/04/88
	4,938,600	07/03/90	Into			02/09/89
	4,967,381	10/30/90	Lane et al.			07/06/89
	5,089,970	02/18/92	Lee et al.			10/05/89
	5,108,570	04/28/92	Wang			03/30/90
	5,208,765	05/04/93	Turnbull			07/20/90
	5,220,517	06/15/93	Sierk et al.			08/31/90
	5,226,118	07/06/93	Baker et al.			01/29/91
	5,231,585	07/27/93	Kobayashi et al.			06/20/90
	5,236,868	08/17/93	Nulman			04/20/90
	5,260,868	11/09/93	Gupta et al.			10/15/91
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(PTO-1449)**ATTY. DOCKET NO.
008019 USA/MTCG/PCTRLSERIAL NO.
10/759,108APPLICANT
Alexander T. SCHWARMFILING DATE
January 20, 2004GROUP
2825**U.S. PATENT DOCUMENTS**

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	3,205,485	09/07/65	Noltingk			10/21/60
	3,229,198	01/11/66	Libby			09/28/62
	3,767,900	10/23/73	Chao et al.			06/23/71
	3,920,965	11/18/75	Sohrwardy			03/04/74
	4,000,458	12/28/76	Miller et al.			08/21/75
	4,207,520	06/10/80	Flora et al.			04/06/78
	4,209,744	06/24/80	Gerasimov et al.			03/27/78
	4,302,721	11/24/81	Urbanek et al.			05/15/79
	4,368,510	01/11/83	Anderson			10/20/80
	4,609,870	09/02/86	Lale et al.			09/13/84
	4,616,308	10/07/86	Morshedi et al.			12/02/85
	4,663,703	05/05/87	Axelby et al.			10/02/85
	4,698,766	10/06/87	Entwistle et al.			05/17/85
	4,750,141	06/07/88	Judell et al.			11/26/85
	4,755,753	07/05/88	Chern			07/23/86
	4,757,259	07/12/88	Charpentier			11/05/86
	4,796,194	01/03/89	Atherton			08/20/86
	4,901,218	02/13/90	Cornwell			03/04/88
	4,938,600	07/03/90	Into			02/09/89
	4,967,381	10/30/90	Lane et al.			07/06/89
	5,089,970	02/18/92	Lee et al.			10/05/89
	5,108,570	04/28/92	Wang			03/30/90
	5,208,765	05/04/93	Turnbull			07/20/90
	5,220,517	06/15/93	Sierk et al.			08/31/90
	5,226,118	07/06/93	Baker et al.			01/29/91
	5,231,585	07/27/93	Kobayashi et al.			06/20/90
	5,236,868	08/17/93	Nulman			04/20/90
	5,260,868	11/09/93	Gupta et al.			10/15/91
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				APPLICANT Alexander T. SCHWARM			
				FILING DATE January 20, 2004		GROUP 2825	
U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
RJ	5,270,222	12/14/93	Moslehi			12/31/90	
	5,283,141	02/01/94	Yoon et al.			03/05/92	
	5,295,242	03/15/94	Mashruwala et al.			11/02/90	
	5,309,221	05/03/94	Fischer et al.			12/31/91	
	5,329,463	07/12/94	Sierk et al.			01/13/93	
	5,338,630	08/16/94	Yoon et al.			11/18/93	
	5,347,446	09/13/94	Iino et al.			02/10/92	
	5,367,624	11/22/94	Cooper			06/11/93	
	5,375,064	12/20/94	Bollinger			12/02/93	
	5,398,336	03/14/95	Tantry et al.			06/16/93	
	5,402,367	03/28/95	Sullivan et al.			07/19/93	
	5,408,405	04/18/95	Mozumder et al.			09/20/93	
	5,410,473	04/25/95	Kaneko et al.			12/16/92	
	5,420,796	05/30/95	Weling et al.			12/23/93	
	5,427,878	06/27/95	Corliss			05/16/94	
	5,469,361	11/21/95	Moyne			06/06/94	
	5,485,082	01/16/96	Wisspeintner et al.			04/05/90	
	5,490,097	02/06/96	Swenson et al.			08/06/93	
	5,495,417	02/27/96	Fuduka et al.			03/16/93	
	5,497,316	03/05/96	Sierk et al.			04/04/95	
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	5,503,707	04/02/96	Maung et al.			09/22/93	
	5,508,947	04/16/96	Sierk et al.			05/13/94	
	5,511,005	04/23/96	Abbe et al.			02/16/94	
	5,519,605	05/21/96	Cawfield			10/24/94	
	5,525,808	06/11/96	Irie et al.			12/20/94	
	5,526,293	06/11/96	Mozumder et al.			12/17/93	
↓	5,534,289	07/09/96	Bilder et al.			01/03/95	
	5,541,510	07/30/96	Danielson			04/06/95	
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				U.S. PATENT DOCUMENTS			
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
RJ	5,546,312	08/13/96	Mozumder et al.			02/24/94	
	5,553,195	09/03/96	Meijer			09/29/94	
	5,586,039	12/17/96	Hirsch et al.			02/27/95	
	5,599,423	02/04/97	Parker et al.			06/30/95	
	5,602,492	02/11/97	Cresswell et al.			04/28/94	
	5,603,707	02/18/97	Trombetta et al.			11/28/95	
	5,617,023	04/01/97	Skalski			02/02/95	
	5,627,083	05/06/97	Tounai			05/12/95	
	5,629,216	05/13/97	Wijaranakula et al.			02/27/96	
	5,642,296	06/24/97	Saxena			07/29/93	
	5,646,870	07/08/97	Krivokapic et al.			02/13/95	
	5,649,169	07/15/97	Berezin et al.			06/20/95	
	5,654,903	08/05/97	Reitman et al.			11/07/95	
	5,655,951	08/12/97	Meikle et al.			09/29/95	
	5,657,254	08/12/97	Sierk et al.			04/15/96	
	5,661,669	08/26/97	Mozumder et al.			06/07/95	
	5,663,797	09/02/97	Sandhu			05/16/96	
	5,664,987	09/09/97	Renteln			09/04/96	
	5,665,199	09/09/97	Sahota et al.			06/23/95	
	5,666,297	09/09/97	Britt et al.			05/13/94	
	5,667,424	09/16/97	Pan			09/25/96	
5,674,787	10/07/97	Zhao et al.			01/16/96		
5,694,325	12/02/97	Fukuda et al.			11/22/95		
5,698,989	12/16/97	Nulman			09/13/96		
5,719,495	02/17/98	Moslehi			06/05/96		
5,719,796	02/17/98	Chen			12/04/95		
5,735,055	04/07/98	Hochbein et al.			04/23/96		
5,740,429	04/14/98	Wang et al.			07/07/95		
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U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
RJ	5,751,582	05/12/98	Saxena et al.			09/24/96	
	5,754,297	05/19/98	Nulman			04/14/97	
	5,761,064	06/02/98	La et al.			10/06/95	
	5,761,065	06/02/98	Kittler et al.			03/30/95	
	5,764,543	06/09/98	Kennedy			06/16/95	
	5,777,901	07/07/98	Berezin et al.			09/29/95	
	5,787,021	07/28/98	Samaha			12/18/95	
	5,787,269	07/28/98	Hyodo			09/19/95	
	5,808,303	09/15/98	Schlagheck et al.			01/29/97	
	5,812,407	09/22/98	Sato et al.			08/12/97	
	5,823,854	10/20/98	Chen			05/28/96	
	5,825,913	10/20/98	Rostami et al.			07/18/95	
	5,828,778	10/27/98	Hagi et al.			07/12/96	
	5,832,224	11/03/98	Fehskens et al.			06/14/96	
	5,838,595	11/17/98	Sullivan et al.			11/25/96	
	5,844,554	12/01/98	Geller et al.			09/17/96	
	5,857,258	01/12/99	Penzes et al.			05/12/94	
	5,859,964	01/12/99	Wang et al.			10/25/96	
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	5,862,054	01/19/99	Li			02/20/97	
	5,863,807	01/26/99	Jang et al.			03/15/96	
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	5,883,437	03/16/99	Maruyama et al.			12/28/95	
	5,889,991	03/30/99	Consolatti et al.			12/06/96	
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5,903,455	05/11/99	Sharpe, Jr. et al.			12/12/96		
5,910,011	06/08/99	Cruse			05/12/97		
5,910,846	06/08/99	Sandhu			08/19/97		
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				APPLICANT Alexander T. SCHWARM			
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U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
RJ	5,912,678	06/15/99	Saxena et al.			04/14/97	
	5,916,016	06/29/99	Bothra			10/23/97	
	5,923,553	07/13/99	Yi			10/05/96	
	5,926,690	07/20/99	Toprac et al.			05/28/97	
	5,930,138	07/27/99	Lin et al.			09/10/97	
	5,940,300	08/17/99	Ozaki			05/08/97	
	5,943,237	08/24/99	Van Boxem			10/17/97	
	5,960,185	09/28/99	Nguyen			06/24/96	
	5,960,214	09/28/99	Sharpe, Jr. et al.			12/04/96	
	5,961,369	10/05/99	Bartels et al.			06/04/98	
	5,963,881	10/05/99	Kahn et al.			10/20/97	
	5,978,751	11/02/99	Pence et al.			02/25/97	
	5,982,920	11/09/99	Tobin, Jr. et al.			01/08/97	
	6,002,989	12/14/99	Shiba et al.			04/01/97	
	6,017,771	01/25/00	Yang et al.			04/27/98	
	6,036,349	03/14/00	Gombar			07/26/96	
	6,041,263	03/21/00	Boston et al.			10/01/97	
	6,041,270	03/21/00	Steffan et al.			12/05/97	
	6,054,379	04/25/00	Yau et al.			02/11/98	
	6,064,759	05/16/00	Buckley et al.			11/06/97	
	6,072,313	06/06/00	Li et al.			06/17/97	
	6,074,443	06/13/00	Venkatesh et al.			01/29/98	
	6,077,412	06/20/00	Ting et al.			10/30/98	
	6,078,845	06/20/00	Friedman			11/25/96	
	6,094,688	07/25/00	Mellen-Garnett et al.			03/12/98	
	6,097,887	08/01/00	Hardikar et al.			10/27/97	
	6,108,092	08/22/00	Sandhu			06/08/99	
↓	6,111,634	08/29/00	Pecen et al.			05/28/97	
	6,112,130	08/29/00	Fukuda et al.			10/01/97	
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
RJ	6,127,263	10/03/00	Parikh			07/10/98	
	6,128,016	10/03/00	Coelho et al.			12/20/96	
	6,136,163	10/24/00	Cheung et al.			03/05/99	
	6,141,660	10/31/00	Bach et al.			07/16/98	
	6,143,646	11/07/00	Wetzel			06/03/97	
	6,148,099	11/14/00	Lee et al.			07/03/97	
	6,148,239	11/14/00	Funk et al.			12/12/97	
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	6,159,075	12/12/00	Zhang			10/13/99	
	6,159,644	12/12/00	Satoh et al.			03/06/96	
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	6,172,756 B1	01/09/01	Chalmers et al.			12/11/98	
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	6,175,777 B1	01/16/01	Kim			01/16/98	
	6,178,390 B1	01/23/01	Jun			09/08/98	
	6,183,345 B1	02/06/01	Kamono et al.			03/20/98	
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	6,197,604 B1	03/06/01	Miller et al.			10/01/98	
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	6,210,983 B1	04/03/01	Atchison et al.			06/15/99	
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	6,214,734 B1	04/10/01	Bothra et al.			11/20/98	
	6,217,412 B1	04/17/01	Campbell et al.			08/11/99	
↓	6,219,711 B1	04/17/01	Chari			10/01/97	
	6,222,936 B1	04/24/01	Phan et al.			09/13/99	
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
RJ	6,226,792 B1	05/01/01	Goiffon et al.			10/14/98	
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	6,248,602 B1	06/19/01	Bode et al.			11/01/99	
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	6,252,412 B1	06/26/01	Talbot et al.			01/08/99	
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↓	6,307,628 B1	10/23/01	Lu et al.			08/18/00	
	6,314,379 B1	11/06/01	Hu et al.			12/04/97	
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RJ	2001/0039462 A1	11/08/01	Mendez et al.			04/02/01	
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	6,320,655 B1	11/20/01	Matsushita et al.			03/15/00	
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	6,395,152 B1	05/28/02	Wang			07/02/99	
	6,397,114 B1	05/28/02	Eryurek et al.			05/03/99	
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↓	6,405,096 B1	06/11/02	Toprac et al.			08/10/99	
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
RJ	2002/0070126 A1	06/13/02	Sato et al.			09/19/01	
	2002/0077031 A1	06/20/02	Johannson et al.			07/06/01	
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	6,479,902 B1	11/12/02	Lopatin et al.			06/29/00	
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	2002/0185658 A1	12/12/02	Inoue et al.			06/14/01	
	2002/0193902 A1	12/19/02	Shanmugasundram et al.			06/18/02	
	2002/0197745 A1	12/26/02	Shanmugasundram et al.			08/31/01	
	2002/0197934 A1	12/26/02	Paik			11/30/01	
	2002/0199082 A1	12/26/02	Shanmugasundram et al.			06/18/02	
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EXAMINER'S INITIALS	PATENT APP. NO.	FILING DATE	NAME	TITLE	CLASS	SUB-CLASS	
RJ	09/363,966	07/29/99	Arackaparambil et al.	Computer Integrated Manufacturing Techniques			
	09/469,227	12/22/99	Somekh et al.	Multi-Tool Control System, Method and Medium			
	09/619,044	07/19/00	Yuan	System and Method of Exporting or Importing Object Data in a Manufacturing Execution System			
	09/637,620	08/11/00	Chi et al.	Generic Interface Builder			
	09/656,031	09/06/00	Chi et al.	Dispatching Component for Associating Manufacturing Facility Service Requestors with Service Providers			
	09/655,542	09/06/00	Yuan	System, Method and Medium for Defining Palettes to Transform an Application Program Interface for a Service			
	09/725,908	11/30/00	Chi et al.	Dynamic Subject Information Generation in Message Services of Distributed Object Systems			
	09/800,980	03/08/01	Hawkins et al.	Dynamic and Extensible Task Guide			
	09/811,667	03/20/01	Yuan et al.	Fault Tolerant and Automated Computer Software Workflow			
	09/927,444	08/13/01	Ward et al.	Dynamic Control of Wafer Processing Paths in Semiconductor Manufacturing Processes			
	09/928,473	08/14/01	Koh	Tool Services Layer for Providing Tool Service Functions in Conjunction with Tool Functions			
	09/928,474	08/14/01	Krishnamurthy et al.	Experiment Management System, Method and Medium			
	09/943,383	08/31/01	Shanmugasundram et al.	In Situ Sensor Based Control of Semiconductor Processing Procedure			
	09/943,955	08/31/01	Shanmugasundram et al.	Feedback Control of a Chemical Mechanical Polishing Device Providing Manipulation of Removal Rate Profiles			
	09/998,372	11/30/01	Paik	Control of Chemical Mechanical Polishing Pad Conditioner Directional Velocity to Improve Pad Life			
✓	09/998,384	11/30/01	Paik	Feedforward and Feedback Control for Conditioning of Chemical Mechanical Polishing Pad			
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EXAMINER'S INITIALS	PATENT APP. NO.	FILING DATE	NAME	TITLE	CLASS	SUB- CLASS	
RJ	10/084,092	02/28/02	Arackaparambil et al.	Computer Integrated Manufacturing Techniques			
↓	10/100,184	03/19/02	Al-Bayati et al.	Method, System and Medium for Controlling Semiconductor Wafer Processes Using Critical Dimension Measurements			
	10/135,405	05/01/02	Reiss et al.	Integration of Fault Detection with Run-to-Run Control			
	10/135,451	05/01/02	Shanmugasundram et al.	Dynamic Metrology Schemes and Sampling Schemes for Advanced Process Control in Semiconductor Processing			
	10/172,977	06/18/02	Shanmugasundram et al.	Method, System and Medium for Process Control for the Matching of Tools, Chambers and/or Other Semiconductor-Related Entities			
	10/173,108	06/18/02	Shanmugasundram et al.	Integrating Tool, Module, and Fab Level Control			
	10/174,370	06/18/02	Shanmugasundram et al.	Feedback Control of Plasma-Enhanced Chemical Vapor Deposition Processes			
	10/174,377	06/18/02	Schwarm et al.	Feedback Control of Sub-Atmospheric Chemical Vapor Deposition Processes			
	10/377,654	03/04/03	Kokotov et al.	Method, System and Medium for Controlling Manufacturing Process Using Adaptive Models Based on Empirical Data			
	10/393,531	03/21/03	Shanmugasundram et al.	Copper Wiring Module Control			
	10/632,107	08/01/03	Schwarm et al.	Method, System, and Medium for Handling Misrepresentative Metrology Data Within an Advanced Process Control System			
	10/665,165	09/18/03	Paik	Feedback Control of a Chemical Mechanical Polishing Process for Multi-Layered Films			
↓	10/712,273	11/14/03	Kokotov	Method, System and Medium for Controlling Manufacture Process Having Multivariate Input Parameters			
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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
RJ	61-66104	04/04/86	Japan			X	
	61-171147	08/01/86	Japan			X	
	01-283934	11/15/89	Japan			X	
	0 397 924 A1	11/22/90	Europe			X	
	2,050,247	08/29/91	Canada			X	
	2,165,847	08/29/91	Canada			X	
	2,194,855	08/29/91	Canada			X	
	3-202710	09/04/91	Japan			X	
	05-151231	06/18/93	Japan			X	
	05-216896	08/27/93	Japan			X	
	05-266029	10/15/93	Japan			X	
	06-110894	04/22/94	Japan			X	
	06-176994	06/24/94	Japan			X	
	06-184434	07/05/94	Japan			X	
	06-252236	09/09/94	Japan			X	
	06-260380	09/16/94	Japan			X	
	EP 0 621 522 A2	10/26/94	Europe			X	
	WO 95/34866	12/21/95	WO			X	
	8-23166	01/23/96	Japan			X	
	08-50161	02/20/96	Japan			X	
	08-149583	06/07/96	Japan			X	
	08-304023	11/22/96	Japan			X	
	EP 0 747 795 A2	12/11/96	Europe			X	
	09-34535	02/07/97	Japan			X	
	9-246547	09/19/97	Japan			X	
	WO 98/05066	02/05/98	WO			X	
↓	10-34522	02/10/98	Japan			X	
	10-173029	06/26/98	Japan			X	
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						Yes	No
RJ	EP 0 869 652 A2	10/07/98	Europe			X	
	WO 98/45090	10/15/98	WO			X	
	EP 0 877 308 A2	11/11/98	Europe			X	
	EP 0 881 040 A2	12/02/98	Europe			X	
	EP 0 895 145 A1	02/03/99	Europe			X	
	WO 99/09371	02/25/99	WO			X	
	11-67853	03/09/99	Japan			X	
	EP 0 910 123 A1	04/21/99	Europe			X	
	11-126816	05/11/99	Japan			X	
	11-135601	05/21/99	Japan			X	
	WO 99/25520	05/27/99	WO			X	
	EP 0 932 194 A1	07/28/99	Europe			X	
	WO 99/59200	11/18/99	WO			X	
	WO 00/00874	01/06/00	WO			X	
	WO 00/05759	02/03/00	WO			X	
	WO 00/35063	06/15/00	WO			X	
	2000-183001	06/30/00	Japan			X	
	WO 00/54325	09/14/00	WO			X	
	GB 2 347 885 A	09/20/00	United Kingdom			X	
	WO 00/79355 A1	12/28/00	WO			X	
	EP 1 066 925 A2	01/10/01	Europe			X	
	EP 1 067 757 A1	01/10/01	Europe			X	
	EP 1 071 128 A2	01/24/01	Europe			X	
	WO 01/11679 A1	02/15/01	WO			X	
	WO 01/15865 A1	03/08/01	WO			X	
	WO 01/18623 A1	03/15/01	WO			X	
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FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
RJ	2001-76982	03/23/01	Japan			X	
	WO 01/25865 A1	04/12/01	WO			X	
	EP 1 092 505 A2	04/18/01	Europe			X	
	WO 01/33277 A1	05/10/01	WO			X	
	WO 01/33501 A1	05/10/01	WO			X	
	434103	05/16/01	Taiwan			X	
	436383B	05/28/01	Taiwan			X	
	WO 01/52055 A3	07/19/01	WO			X	
	WO 01/52319 A1	07/19/01	WO			X	
	WO 01/57823 A2	08/09/01	WO			X	
	455938B	09/21/01	Taiwan			X	
	455976	09/21/01	Taiwan			X	
	2001-284299	10/12/01	Japan			X	
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	2001-305108	10/31/01	Japan			X	
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